

Abstract

Cooling system for devices comprising power semiconductors and method for cooling said type of device

The invention relates to a cooling system (22) for devices comprising power semiconductors (1) and a method for cooling said type of device. For this purpose, the cooling system has printed circuit boards (4) arranged on a circuit carrier (10) in plug-in contact strips (7). The cooling system itself has a cooling plate (11), which is mounted in a pivotable manner on one of the plug-in contact strips (7) in the region of the power semiconductor component (1). The cooling plate (11) can be pivoted about an axis (14) in such a way that it assumes a first position, which is pivoted away from the printed circuit board (4), and a second position, in which the cooling plate (11) bears on the power semiconductor component (1).

[Figure 1]